

Title (en)

POSITIVE WORKING PHOTODEFINABLE RESIN COATED METAL FOR MASS PRODUCTION OF MICROVIAS IN MULTILAYER PRINTED WIRING BOARDS

Title (de)

MIT POSITIV ARBEITENDEM PHOTOSTRUKTURIER BAREM HARZ BESCHICHTETES METALL ZUR MASSENHERSTELLUNG VON MIKROKONTAKTLÖCHERN IN MEHRSCICHTIGEN LEITERPLATTEN

Title (fr)

METAL REVETU DE RESINE POSITIVE PHOTO-DEFINISSABLE POUR PRODUCTION DE MASSE DE TROUS D'INTERCONNEXION A L'ECHELLE MICROSCOPIQUE DANS DES TABLEAUX DE CONNEXIONS MULTICOUCHE IMPRIMES

Publication

**EP 0976307 A1 20000202 (EN)**

Application

**EP 98914668 A 19980413**

Priority

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- US 4432797 P 19970416
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Abstract (en)

[origin: WO9847332A1] High density built-up multilayer printed circuit boards are produced by constructing microvias with positive working photoimageable dielectric materials. A positive working photosensitive dielectric composition (4) on a conductive foil (2) is laminated to conductive lines (6) on a substrate (8). After imaging the foil (2), and imaging and curing the photosensitive dielectric composition (4), vias (14) are formed to the conductive lines (6). Thereafter the conductive lines (6) are connected (16) through the vias (14) to the conductive foil (2), and then the conductive foil (2) is patterned.

IPC 1-7

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IPC 8 full level

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CPC (source: EP KR)

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Citation (search report)

See references of WO 9847332A1

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